



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



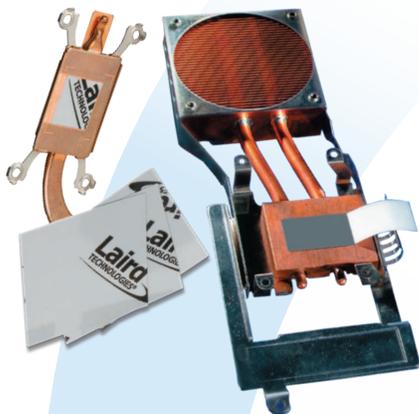
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FOR EXCEPTIONALLY LOW THERMAL RESISTANCE

The Tmate™ 2900 Series is a reusable phase change material (PCM) designed for ease of testing and rework ability. It has a composite construction of a special malleable metal alloy and a high-performance PCM.

At 50°C, the Tmate 2900 Series begins to soften and flow, filling the microscopic irregularities of the thermal solution, thus reducing thermal resistance.

It shows no thermal performance degradation after 1,000 hours @130°C, or after 500 cycles from -25°C to 125°C. The PCM softens and does not fully change state, resulting in minimal migration (pump-out) at operating temperatures (see viscosity curve). It is available in three thicknesses: 0.005" (0.125 mm), 0.010" (0.25 mm), and 0.020" (0.5 mm).

FEATURES AND BENEFITS

- Low thermal resistance at low pressures
- Reusable: make and break thermal interface connection many times
- Naturally tacky at room temperature, no adhesive required
- No heat sink preheating required

APPLICATIONS

- High frequency microprocessors
- Notebook and desktop PCs
- Computer servers
- Thermal test stands

global solutions: local support.™

Americas: +1.888.246.9050

Europe: +46.31.704.67.57

Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

SPECIFICATIONS

PROPERTIES	Tmate™ 2905c	Tmate™ 2910c	Tmate™ 2920	TEST METHOD
Construction & composition	Foil reinforced boron nitride filled film			
Color	Yellow/Silver			Visual
Thickness	0.005" (0.13 mm)	0.010" (0.25 mm)	0.020" (0.51 mm)	
Thickness tolerance	± 0.001" (±0.03 mm)	± 0.001" (±0.03 mm)	± 0.002" (±0.05 mm)	
Density	1.86 g/cc	1.64 g/cc	1.52 g/cc	Helium Pycnometer
Shelf life	1 Year			
Temperature range	-25°C to 125°C			
Phase change softening temperature	50°C to 70°C			
"Burn-In" temperature	70°C for 5 min			
Thermal impedance				
@20 psi	0.07°C-in ² /W	0.09°C-in ² /W	0.27°C-in ² /W	ASTM D5470 (modified)
@130 KPa	0.45°C-cm ² /W	0.61°C-cm ² /W	1.74°C-cm ² /W	
Volume resistivity	5 x 10 ¹² ohm-cm			ASTM D257
Dielectric constant @ 1 MHz	4.2			ASTM D150

Standard Thicknesses: 0.005" (0.13 mm) 0.010" (0.25 mm) 0.020" (0.51 mm)
Consult the factory for alternate thicknesses

Standard Sheet Sizes: 9" x 9" (229 mm x 229 mm)

Tmate™ 2900 sheets are supplied with a clear polyester top liner to protect phase change material.

Tmate™ 2900 is available in individual die cut shapes.

Adhesive: Pressure sensitive adhesive is not applicable for Tmate™ products.

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